

AMENDMENTS TO THE ABSTRACT:

Please amend the Abstract originally appearing on page 28 of the application as follows:

ABSTRACT OF THE DISCLOSURE

A stackable ball grid array (BGA) or fine ball grid array (FBGA) semiconductor package particularly suitable for board-on-chip or chip-on-board applications in which a ~~low-profile~~ low-profile BGA or FBGA semiconductor package is needed. The stackable ball grid array (BGA) or fine ball grid array (FBGA) provides a semiconductor package that is capable of being ~~burned-in~~ burned-in and tested in a more efficient and ~~cost-effective~~ cost-effective manner than prior known BGA or FBGA semiconductor packages. A ~~high-density, low-profile~~ high-density, low-profile memory module incorporating a plurality of the disclosed BGA or FBGA semiconductor packages in a stacked arrangement is further disclosed.